### June/2004

## MITSUBISHI SEMICONDUCTOR <GaAs FET> MGF4953A/MGF4954A

SUPER LOW NOISE InGaAs HEMT (Leadless Ceramic Package)

DESCRIPTION	
The MGF4953A/MGF4954A super-low noise HEMT (High	
Electron Mobility Transistor) is designed for use in C to K I	
amplifiers.	
The lead-less ceramic package assures minimum paras	tic losses.
FEATURES	
Low noise figure @ f=12GHz	
MGF4953A : NFmin. = 0.40dB (Typ.)	
MGF4954A : NFmin. = 0.60dB (Typ.)	Fig.1
High associated gain @ f=12GHz	
Gs = 13.5dB (Typ.)	
APPLICATION	MITSUBISHI Proprietary
C to K band low noise amplifiers	Not to be reproduced or disclosed without permission by Mitsubishi Electric
QUALITY GRADE	
GG	
RECOMMENDED BIAS CONDITIONS	
$V_{DS}=2V$ , $I_{D}=10mA$	
ORDERING INFORMATION	
Tape & reel 3000pcs./reel	
	Koon Sofaty first in your sireuit designal
	Keep Safety first in your circuit designs! Mitsubishi Electric Corporation puts the maximum
	effort into making semiconductor products better
	and more reliable, but there is always the
	possibility that trouble may occur with them.
ABSOLUTE MAXIMUM RATINGS (Ta=25°C)	Trouble with semiconductors may lead to personal injury, fire or property damage. Remember to give
	,, ,

Symbol	Parameter	Ratings	Unit
V <sub>GDO</sub>	Gate to drain voltage	-4	V
V <sub>GSO</sub>	Gate to source voltage	-4	V
I <sub>D</sub>	Drain current	60	mA
PT	Total power dissipation	50	mW
T <sub>ch</sub>	Channel temperature	125	°C
T <sub>stg</sub>	Storage temperature	-65 to +125	°C

due consideration to safety when making your circuit designs , with appropriate measure such as (I) placement of substitutive , auxiliary circuits , (ii) use of non-flammable material or (iii) prevention against any malfunction or mishap.

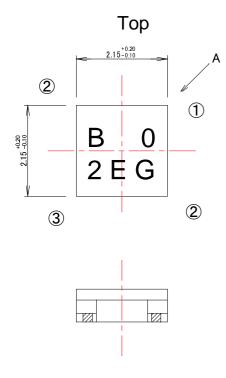
#### ELECTRICAL CHARACTERISTICS (Ta=25°C)

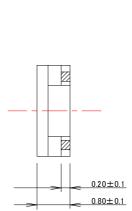
Synbol	Parameter	Test conditions		Limits			Unit
					TYP.	MAX	
V <sub>(BR)</sub> GDO	Gate to drain breakdown voltage	I <sub>G</sub> =-10μΑ		-3			V
I <sub>GSS</sub>	Gate to source leakage current	V <sub>GS</sub> =-2V,V <sub>DS</sub>	3=0V			50	μΑ
IDSS	Saturated drain current	V <sub>GS</sub> =0V,V <sub>DS</sub> :	=2V	15		60	mA
V <sub>GS(off)</sub>	Gate to source cut-off voltage	V <sub>DS</sub> =2V,I <sub>D</sub> =5	00μΑ	-0.1		-1.5	V
gm	Transconductance	V <sub>DS</sub> =2V,I <sub>D</sub> =1	V <sub>DS</sub> =2V,I <sub>D</sub> =10mA		70		mS
Gs	Associated gain	V <sub>DS</sub> =2V,	V <sub>DS</sub> =2V,		13.5		dB
NFmin.	Minimum noise figure	I <sub>D</sub> =10mA	MGF4953A		0.40	0.50	dB
		f=12GHz	MGF4954A		0.60	0.80	dB

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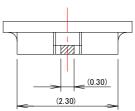
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Fig.1



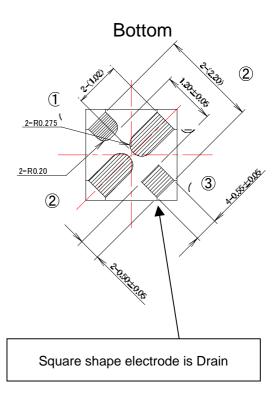


Side



from "A" side view

Unit : mm





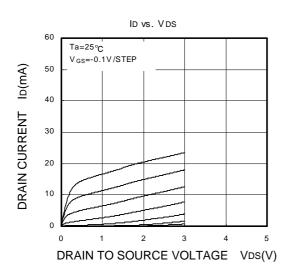
# MITSUBISHI

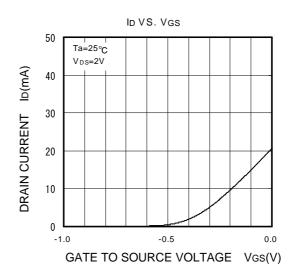
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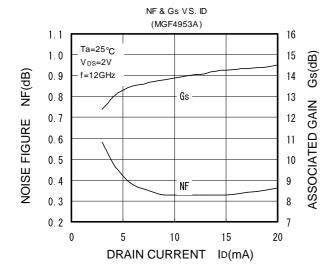
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## MITSUBISHI SEMICONDUCTOR <GaAs FET> MGF4953A/MGF4954A

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# **S PARAMETERS**

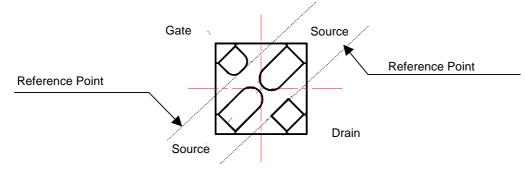
#### (Ta=25°C,VDS=2V,ID=10mA)

Freq	S	11	S	21	S12		2 \$22	
(GHz)	(mag)	(ang)	(mag)	(ang)	(mag)	(ang)	(mag)	(ang)
1	0.911	-12.7	4.924	168.1	0.008	70.3	0.709	-10.7
2	0.894	-29.2	4.806	155.3	0.031	68.8	0.691	-22.7
3	0.875	-40.7	4.796	142.7	0.043	62.2	0.682	-30.1
4	0.858	-53.9	4.672	131.6	0.061	49.4	0.652	-41.7
5	0.830	-66.5	4.524	121.2	0.066	42.9	0.639	-49.6
6	0.797	-77.7	4.308	109.5	0.073	33.5	0.631	-58.5
7	0.770	-87.0	4.114	101.1	0.080	26.2	0.628	-64.4
8	0.751	-94.2	3.984	90.8	0.089	22.1	0.625	-71.0
9	0.727	-103.0	3.886	81.4	0.090	17.4	0.624	-76.1
10	0.713	-110.8	3.881	75.0	0.101	9.2	0.628	-80.4
11	0.686	-119.9	3.886	66.0	0.110	2.2	0.612	-87.5
12	0.636	-132.8	3.937	54.7	0.120	-4.6	0.581	-94.3
13	0.590	-146.6	4.078	45.0	0.127	-13.0	0.540	-101.0
14	0.538	-165.8	4.163	31.5	0.136	-25.2	0.485	-112.5
15	0.507	170.2	4.239	18.9	0.144	-35.8	0.396	-122.4
16	0.506	140.8	4.238	4.5	0.151	-48.2	0.283	-137.3
17	0.552	110.4	4.067	-10.5	0.151	-62.0	0.159	-162.3
18	0.625	86.0	3.791	-26.5	0.145	-74.0	0.076	120.8
19	0.696	65.9	3.428	-40.5	0.137	-85.8	0.164	54.1
20	0.745	50.8	3.045	-54.3	0.118	-97.6	0.271	31.6
21	0.791	38.2	2.677	-66.5	0.109	-106.8	0.375	20.9
22	0.794	28.2	2.281	-76.2	0.102	-114.0	0.455	14.3
23	0.776	18.4	1.984	-84.5	0.091	-118.9	0.539	8.5
24	0.802	11.0	1.828	-93.8	0.078	-127.7	0.607	5.7
25	0.796	2.9	1.626	-102.1	0.071	-130.2	0.675	2.1
26	0.799	-8.5	1.424	-114.5	0.064	-138.3	0.730	0.9

# NOISE PARAMETERS (Ta=25°C,VDS=2V,ID=10mA)

f	Gamn	na-opt	Rn	NFmin.	Gs
(GHz)	Magn.	Angle	(ohm)	(dB)	(dB)
4	0.64	52.7	0.27	0.22	18.3
8	0.61	103.5	0.15	0.28	15.9
12	0.55	146.4	0.06	0.35	13.5
14	0.51	161.9	0.04	0.39	12.5
18	0.41	175.3	0.03	0.48	11.0
20	0.35	-177.3	0.05	0.55	10.5

Note) Rn is normalized by 50-ohm



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